



# TECHNICAL DATA SHEET

CATEGORY: **ALLOY**  
NAME: **Sn99.3/Cu0.7**

## FEATURES

- HIGH PURITY
- HIGH TEMPERATURE- 227°C

## DESCRIPTION

Sn99.3/Cu0.7 is a eutectic alloy used for high-temperature applications and lead-free applications. Tin/Copper alloys are typically used in electronic assembly, die attach, thick film, and other applications in which the use of lead is prohibitive. These alloys are generally available in wire, bar, preforms, powder, solder paste, ingot, and anode form.

## IMPURITY LEVELS TO IPC-JSTD-006 in Percent

Al: 0.005	Ag: 0.10	Fe: 0.02	Pb: 0.10
As: 0.03	Bi: 0.10	In: 0.10	Sb: 0.50
Au: 0.05	Cd: 0.002	Ni: 0.01	Zn: 0.003

## HANDLING

- There are no special handling or storage requirements for this product.

## FLUX COMPATIBILITY

- Tin/Copper Alloys are compatible with most electronic- and industrial-grade fluxes.

## CLEANING

- Refer to data sheets provided by the flux manufacturer.

## SAFETY

- Use with adequate ventilation and proper personal protective equipment.
- Refer to the accompanying **Material Safety Data Sheet** for any specific emergency information.
- Do not dispose of any hazardous materials in non-approved containers.

The information contained herein is based on data considered accurate and is offered at no charge. No warranty is expressed or implied regarding the accuracy of this data. Liability is expressly disclaimed for any loss or injury arising out of the use of this information or the use of any materials designated.

Manufacturing and Distribution Worldwide  
Americas +1-401-463-5605 • Europe +44-1737-222-258 • Asia-Pacific +852-2649-7183 • info@aimsolder.com • www.aimsolder.com